

S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Kie Y. Ahn et al.	Examiner:	Unknown
Serial No.:	Unknown	Group Art Unit:	Unknown
Filed:	Herewith	Docket:	303.685US2
Title:	MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION		

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

Pursuant to 37 C.F.R. §1.98(d), copies of some of the listed documents are not provided as these references were previously cited by or submitted to the U.S. Patent Office in connection with Applicants' prior U.S. application, Serial No. 09/584157, filed on May 31, 2000, which is relied upon for an earlier filing date under 35 U.S.C. §120.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No :Unknown

Filing Date: Herewith

Title: MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION

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Applicant believes that the U.S. Patent & Trademark Office has waived the requirement under 37 C.F.R. 1.98 (a)(2)(i) for submitting a copy of each cited U.S. patent and each U.S. patent application publication. The waiver is provided in a pre-OG notice from the U.S. Patent & Trademark Office entitled "Information Disclosure Statements May Be Filed Without Copies of U.S. Patents and Published Applications in Patent Applications filed after June 30, 2003" and dated July 11, 2003. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.


By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-9587

Date

24 Nov '03

By



Timothy B. Clise

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Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known	
	Applicant Number	Unknown
	Filing Date	Even Date Herewith
	First Named Inventor	Ahn, Kie
	Group Art Unit	Unknown
	Examiner Name	Unknown
Sheet 1 of 9		Attorney Docket No: 303.685US2

US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-2001/0002333	05/31/2001	Huang, Chao-Yuan , et al.	438	637	03/29/1999
	US-1,254,987	01/29/1918	Cooper, H. S.			10/15/1917
	US-1,976,375	10/09/1934	Smith, J. K.	148	11.5	01/27/1931
	US-2001/0054771	12/27/2001	Wark, J. M., et al.			
	US-2002/0014646	02/07/2002	Tsu, et al.	257	296	
	US-2002/0028552	03/07/2002	Lee, et al.	438	243	
	US-2002/0096768	07/25/2002	Joshi, Rajiv Vasant	257	750	
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	US-2,244,608	06/03/1941	Cooper, H. S.	75	138	02/09/1939
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	US-3,923,500	12/02/1975	Kitazawa, Kunio , et al.	75	156.5	09/04/1974
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	US-4,022,931	05/10/1977	Black, J. , et al.	427	91	06/13/1975
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	US-4,065,330	12/27/1977	Masumoto, Hakaru , et al.	148	31.55	02/22/1977
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Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached

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**INFORMATION DISCLOSURE
 STATEMENT BY APPLICANT**
 (Use as many sheets as necessary)

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Application Number	Unknown
Filing Date	Even Date Herewith
First Named Inventor	Ahn, Kie
Group Art Unit	Unknown
Examiner Name	Unknown

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Attorney Docket No: 303.685US2

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Applicant Number	Unknown
Filing Date	Even Date Herewith
First Named Inventor	Ahn, Kie
Group Art Unit	Unknown
Examiner Name	Unknown

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Substitute Disclosure Statement Form (PTO-1449)

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	Application Number	Unknown
	Filing Date	Even Date Herewith
	First Named Inventor	Ahn, Kie
	Group Art Unit	Unknown
	Examiner Name	Unknown
Sheet 4 of 9	Attorney Docket No: 303.685US2	

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	US-5,895,740	04/20/1999	Chien, Rong-Wu , et al.	430	313	11/13/1996
	US-5,897,370	04/27/1999	Joshi, R. V., et al.	438	632	10/28/1996
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	US-5,925,930	07/20/1999	Farnworth, Warren M., et al.	257	737	05/21/1996
	US-5,930,669	07/27/1999	Uzoh, Cyprian	438	627	04/03/1997
	US-5,932,928	08/03/1999	Clampitt, D. A.	257	758	07/03/1997
	US-5,940,733	08/17/1999	Beinglass, Israel , et al.	438	655	07/29/1997
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	US-5,994,777	11/30/1999	Farrar, P. A.	257	758	08/26/1998
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	US-6,017,820	01/25/2000	Ting, C. H., et al.	438	689	07/17/1998
	US-6,025,261	02/15/2000	Farrar, C. , et al.	438	619	04/29/1998
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	US-6,065,424	05/23/2000	Shacham-Diamand, Y. , et al.	118	696	12/18/1996
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Gr up Art Unit	Unknown
Examiner Name	Unknown

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	US-6,136,095	10/24/2000	Xu, Z. , et al.	118	719	10/06/1997
	US-6,139,699	10/31/2000	Chiang, T. , et al.	204	192.15	05/27/1997
	US-6,140,228	10/31/2000	Shan, E. , et al.	438	653	11/13/1997
	US-6,140,234	10/31/2000	Uzoh, Cyprian , et al.	438	678	01/20/1998
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	US-6,288,442	09/11/2001	Farrar, Paul A.	257	678	09/10/1998
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	Group Art Unit	Unknown
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